

LEAD FRAME

Patent Number: JP60231349
 Publication date: 1985-11-16
 Inventor(s): KOGA NOBUHIRO
 Applicant(s):: TOSHIBA KK
 Requested Patent: ☒ JP60231349
 Application JP19840088165 19840501
 Priority Number(s):
 IPC Classification: H01L23/48
 EC Classification:
 Equivalents:

Abstract

PURPOSE: To improve moisture resistance with respect to a semiconductor element, which is enclosed in a package, and to facilitate the deburring of a molding resin, by differentiating the surface roughnesses and the surface materials of an outer lead part and an inner lead part.
CONSTITUTION: For an outer lead part 2a, a material having a smooth surface roughness is used. Thus adhesion is made low and the burr of a molding resin is hard to attach. Therefore the deburring becomes easy. The surface roughness of the material of only the part of an inner lead part 2b of a lead 2 is made rough by lapping, press or the like, and the adhesion of the inner lead part is made good. Or a partial plated layer 6 is provided the inner lead part 2b. The wire bonding between a semiconductor element 8 and the lead 2 is made easy. Or a plated layer 7 is attached only to the inner lead part 2b and the different material can be formed.

Data supplied from the esp@cenet database - 12